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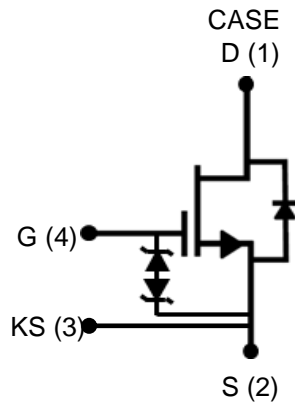
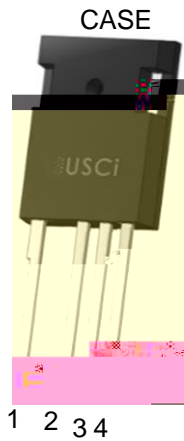


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# DATASHEET

# UF3C065030K4S



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Rev. , January 20 % OE

## Description

United Silicon Carbide's cascode products co-package its high-performance F3 SiCfast JFETs with a cascode optimized MOSFET to produce the only standard gate drive SiC device in the market today. This series exhibits very fast switching using a 4-terminal TO-247- package and the best reverse recovery characteristics of any device of similar ratings. These devices are excellent for switching inductive loads, and any application requiring standard gate drive.

## Features

## Typical applications

- EV charging
- PV inverters
- Switch mode power supplies
- Power factor correction module (T<sub>th</sub> 14.5-8 (d) 3.46 (s) 3.213 0 ThmAduc)JTf

Part Number	Package	Marking
UF3C065030K4S	TO-247-4L	UF3C065030K4S







## Electrical Characteristics ( $T_J = +25^\circ\text{C}$ unless otherwise specified)

### Typical Performance - Static

	Min	Typ	Max	
$BV_{DS}$	650			V
		6	150	
		30		
$I_{GSS}$		6	20	FA
		27	35	
		43		
V				



## Typical Performance - Dynamic

Min

Typ

Max



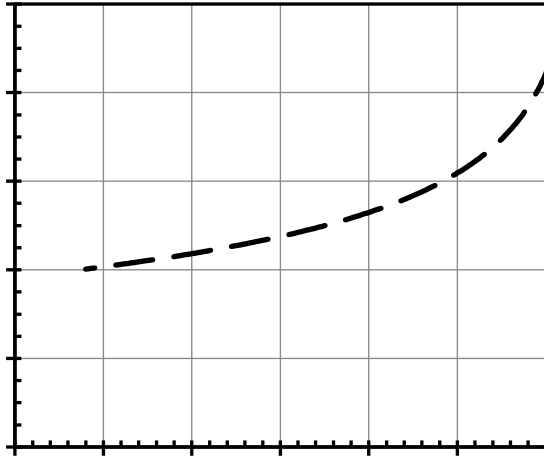


Figure 5. Typical drain-source on-resistances at  $V_{GS} = 12V$

Figure 6. Typical transfer characteristics at  $V_{DS} = 5V$

Figure 7. Threshold voltage vs. junction temperature at  $V_{DS} = 5V$  and  $I_D = 10mA$

Figure 8. Typical gate charge at  $V_{GS} = 400V$  and  $I_D = 50A$







Figure 13. Typical capacitances at  $f = 100\text{kHz}$  and  $V_{GS} = 0\text{V}$

Figure 14. DC drain current derating

Figure 15. Total power dissipation

Figure 16. Maximum transient thermal impedance

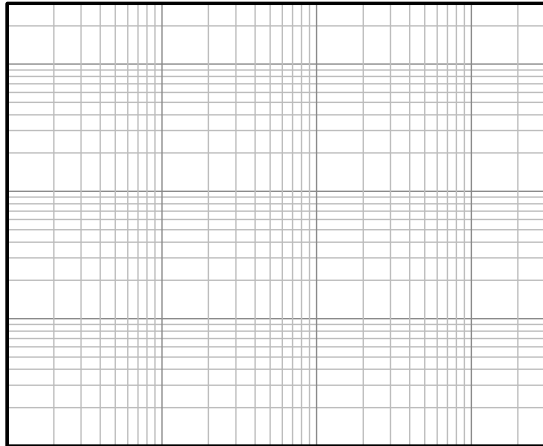


Figure 17. Safe operation area at  $T_c = 25^\circ\text{C}$ ,  $D = 0$ , Parameter  $t_p$

Figure 18. Clamped inductive switching energy vs. drain current at  $T_J = 25^\circ\text{C}$

Figure 19. Clamped inductive switching turn-on energy vs.  $R_{G,EXT\_ON}$

Figure 20. Clamped inductive switching turn-off energy vs.  $R_{G,EXT\_OFF}$



Figure 21. Clamped inductive switching energy vs. junction temperature at  $V_{DS} = 400V$  and  $I_D = 50A$

Figure 22. Reverse recovery charge  $Q_{rr}$  vs. junction temperature

## Applications Information

SiC cascodes are enhancement-mode power switches formed by a high-voltage SiC depletion-mode JFET and a low-voltage silicon MOSFET connected in series.

United Silicon Carbide, Inc. assumes no liability whatsoever relating to the choice, selection or use of the United Silicon Carbide, Inc. products and services described herein.

Like other high performance power switches, proper PCB layout design to minimize circuit parasitics is strongly recommended due to the high  $dv/dt$  and  $di/dt$  rates. An external gate resistor is recommended when the cascode is working in the diode mode in order to achieve the optimum reverse recovery performance. For more information on cascode operation, see [www.unitedsic.com](http://www.unitedsic.com).

## Disclaimer

United Silicon Carbide, Inc. reserves the right to change or modify any of the products and their inherent physical and technical specifications without prior notice. United Silicon Carbide, Inc. assumes no responsibility or liability for any errors or inaccuracies within.





PART MARKING

TO-247-4L PACKAGE  
OUTLINE, PART MARKING  
AND TUBE SPECIFICATIONS

PACKING TYPE

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